



Product Change Notification / KSRA-16XDWZ131

Date:

23-Feb-2021

Product Category:

Memory

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4198.002 Final Notice: Qualification of ASSH as a new assembly site for selected 25AA640xx and 25LC640xx device families of 36K wafer technology available in 8L TSSOP package.

Affected CPNs:

[KSRA-16XDWZ131_Affected_CPN_02232021.pdf](#)

[KSRA-16XDWZ131_Affected_CPN_02232021.csv](#)

Notification Text:

PCN Status: Final notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of ASSH as a new assembly site for selected 25AA640xx and 25LC640xx device families of 36K wafer technology available in 8L TSSOP package.

Pre Change:

Assembled at ANAP using gold (Au) bond wire, 8290 die attach material, G700A molding compound material, with Matte tin lead plating finish and using lead frame without lead lock

Assembled at UNIS using gold (Au) bond wire, 8290 die attach material, G600 molding compound material, with Matte tin lead plating finish and using lead frame without lead lock

Assembled at NSEB using gold (Au) bond wire, 2200D die attach material, G600 molding compound material, with Matte tin

lead plating finish and using lead frame with lead lock

Assembled at MMT using gold (Au) bond wire, 2200D die attach material, G600V molding compound material, with Matte tin lead plating finish and using lead frame without lead lock

Post Change:Assembled at ANAP using gold (Au) bond wire, 8290 die attach material, G700A molding compound material, with Matte tin lead plating finish and using lead frame without lead lock

Assembled at UNIS using gold (Au) bond wire, 8290 die attach material, G600 molding compound material, with Matte tin lead plating finish and using lead frame without lead lock

Assembled at NSEB using gold (Au) bond wire, 2200D die attach material, G600 molding compound material, with Matte tin lead plating finish and using lead frame with lead lock

Assembled at MMT using gold (Au) bond wire, 2200D die attach material, G600V molding compound material, with Matte tin lead plating finish and using lead frame without lead lock

Assembled at ASSH using palladium coated copper (PdCu) bond wire, EN-4900GC die attach material, G700LY molding compound material, with PPF lead plating finish and using lead frame with lead lock

Pre and Post Change Summary:

	Pre Change				Post Change				
Assembly Site	Amkor Technology Philippine (P1/P2), INC. / ANAP	Unisem (M) Berhad Perak, Malaysia / UNIS	UTAC Thai Limited (UTL-1) LTD. / NSEB	Microchip Technology Thailand / MMT	Amkor Technology Philippine (P1/P2), INC. / ANAP	Unisem (M) Berhad Perak, Malaysia / UNIS	UTAC Thai Limited (UTL-1) LTD. / NSEB	Microchip Technology Thailand / MMT	ASE Advanced Semiconduct or (Shanghai) Co., Ltd / ASSH
Wire material	Au	Au	Au	Au	Au	Au	Au	Au	PdCu
Die attach material	8290	8290	2200D	2200D	8290	8290	2200D	2200D	EN-4900GC
Molding compound material	G700A	G600	G600	G600V	G700A	G600	G600	G600V	G700LY
Lead frame material	C7025	C7025	C7025	C7025	C7025	C7025	C7025	C7025	C7025
Lead Plating Finish	Matte tin	Matte tin	Matte tin	Matte tin	Matte tin	Matte tin	Matte tin	Matte tin	PPF
Lead frame lead-lock	See Pre and Post Change attachment for lead frame comparison.								

Impacts to Data Sheet: None

Change Impact:None

Reason for Change:To improve on-time delivery performance by qualifying ASSH as a new assembly site.

Change Implementation Status:In Progress

Estimated First Ship Date:

March 23, 2021 (date code: 2113)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	February 2021				March 2021				
Workweek	06	07	08	09	10	11	12	13	14
Qual Report Availability			X						
Final PCN Issue Date			X						
Estimated Implementation Date								X	

Method to Identify Change: Traceability code

Qualification Report Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:**February 23, 2021:** Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on March 23, 2021

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_KSRA-16XDWZ131_Pre and Post Change Summary.pdf](#)

[PCN_KSRA-16XDWZ131_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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